

L Number	Hits	Search Text	DB	Time stamp
1	37	257/787.ccls. and die and substrate and bump\$2 and metal and material and fill 257/787.	USPAT	2004/03/02 10:54
-	0		USPAT	2004/03/02 09:45
-	1200	257/787.ccls.	USPAT	2004/03/02 09:48
-	614	257/787.ccls. and die	USPAT	2004/03/02 09:48
-	408	257/787.ccls. and die and substrate	USPAT	2004/03/02 09:48
-	157	257/787.ccls. and die and substrate and bump\$2	USPAT	2004/03/02 09:49
-	111	257/787.ccls. and die and substrate and bump\$2 and metal	USPAT	2004/03/02 09:49
-	105	257/787.ccls. and die and substrate and bump\$2 and metal and material	USPAT	2004/03/02 09:49
-	2	257/787.ccls. and die and substrate and bump\$2 and metal and material and fill and affinity	USPAT	2004/03/02 09:50